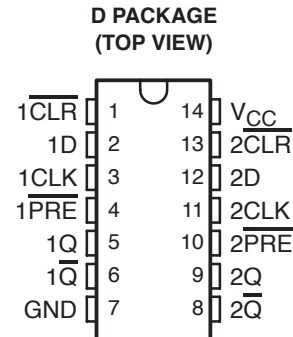


SN74AC74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

SCAS721 – OCTOBER 2003

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **2-V to 6-V V_{CC} Operation**
- **Inputs Accept Voltages to 6 V**
- **Max t_{pd} of 10 ns at 5 V**



† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

description/ordering information

The SN74AC74 is a dual positive-edge-triggered D-type flip-flop.

A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) input sets or resets the outputs, regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the data (D) input meeting the setup-time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at D can be changed without affecting the levels at the outputs.

ORDERING INFORMATION

T _A	PACKAGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	SOIC – D Tape and reel	SN74AC74MDREP	SAC74MEP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS				OUTPUTS	
\overline{PRE}	\overline{CLR}	CLK	D	Q	\overline{Q}
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H§	H§
H	H	↑	H	H	L
H	H	↑	L	L	H
H	H	L	X	Q ₀	\overline{Q}_0

§ This configuration is nonstable; that is, it does not persist when either \overline{PRE} or \overline{CLR} returns to its inactive (high) level.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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SN74AC74-EP

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1	V
		V _{CC} = 4.5 V	3.15	
		V _{CC} = 5.5 V	3.85	
V _{IL}	Low-level input voltage	V _{CC} = 3 V	0.9	V
		V _{CC} = 4.5 V	1.35	
		V _{CC} = 5.5 V	1.65	
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V	-12	mA
		V _{CC} = 4.5 V	-24	
		V _{CC} = 5.5 V	-24	
I _{OL}	Low-level output current	V _{CC} = 3 V	12	mA
		V _{CC} = 4.5 V	24	
		V _{CC} = 5.5 V	24	
Δt/Δv	Input transition rise or fall rate		8	ns/V
T _A	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V _{OH}	I _{OH} = -50 μA	3 V	2.9	4.49	2.9	V		
		4.5 V	4.4	5.49	4.4			
		5.5 V	5.4	5.49	5.4			
	I _{OH} = -12 mA	3 V	2.56		2.4			
		4.5 V	3.86		3.7			
		5.5 V	4.86		4.7			
V _{OL}	I _{OL} = 50 μA	3 V	0.002	0.1	0.1	V		
		4.5 V	0.001	0.1	0.1			
		5.5 V	0.001	0.1	0.1			
	I _{OL} = 12 mA	3 V		0.36	0.5			
		4.5 V		0.36	0.5			
		5.5 V		0.36	0.5			
I _I	Data pins	V _I = V _{CC} or GND	5.5 V		±0.1	±1	μA	
	Control pins				±0.1	±1		
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V		2	40	μA		
C _i	V _I = V _{CC} or GND	5 V		3		pF		

SN74AC74-EP

DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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timing requirements over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
f_{clock}	Clock frequency	100		70		MHz
t_w	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	5.5	8		ns
		CLK	5.5	8		
t_{su}	Setup time, data before $\text{CLK}\uparrow$	Data	4	5		ns
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	0	0.5		
t_h	Hold time, data after $\text{CLK}\uparrow$	0.5	0.5			ns

timing requirements over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

		$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
		MIN	MAX			
f_{clock}	Clock frequency	140		95		MHz
t_w	Pulse duration	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ low	4.5	5.5		ns
		CLK	4.5	5.5		
t_{su}	Setup time, data before $\text{CLK}\uparrow$	Data	3	4		ns
		$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive	0	0.5		
t_h	Hold time, data after $\text{CLK}\uparrow$	0.5	0.5			ns

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT	
			MIN	TYP	MAX				
f_{max}			100	125		70		MHz	
t_{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or \overline{Q}	3.5	8	12	1	13		ns
t_{PHL}			4	10.5	12	1	14		
t_{PLH}	CLK	Q or \overline{Q}	4.5	8	13.5	1	17.5		ns
t_{PHL}			3.5	8	14	1	13.5		

switching characteristics over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

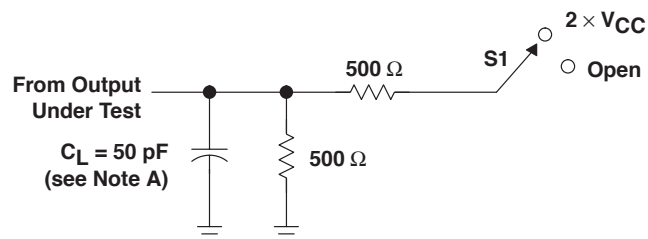
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT	
			MIN	TYP	MAX				
f_{max}			140	160		95		MHz	
t_{PLH}	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or \overline{Q}	2.5	6	9	1	9.5		ns
t_{PHL}			3	8	9.5	1	10.5		
t_{PLH}	CLK	Q or \overline{Q}	3.5	6	10	1	12		ns
t_{PHL}			2.5	6	10	1	10		

operating characteristics, $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	45	pF

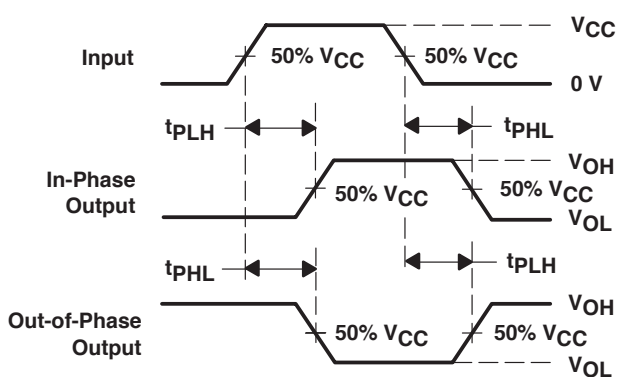


PARAMETER MEASUREMENT INFORMATION

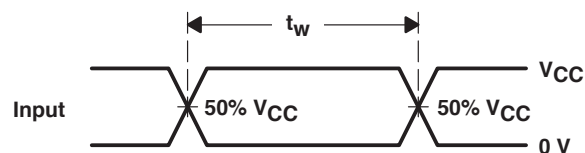


LOAD CIRCUIT

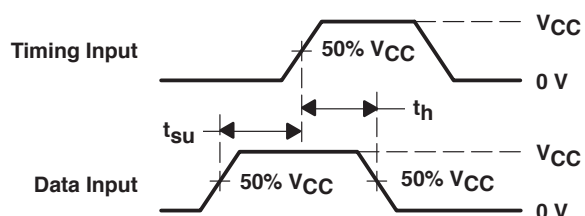
TEST	S1
t_{PLH}/t_{PHL}	Open



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.

C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AC74MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/04617-01XE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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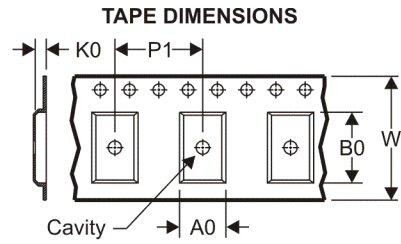
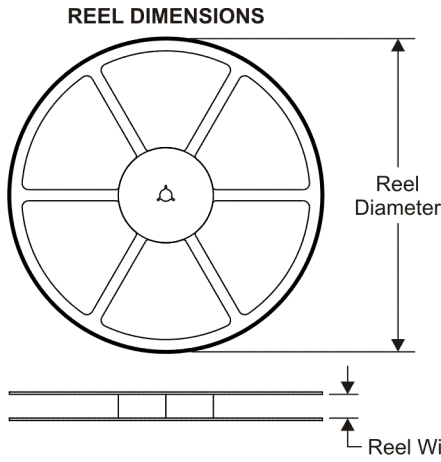
OTHER QUALIFIED VERSIONS OF SN74AC74-EP :

- Catalog: [SN74AC74](#)
- Military: [SN54AC74](#)

NOTE: Qualified Version Definitions:

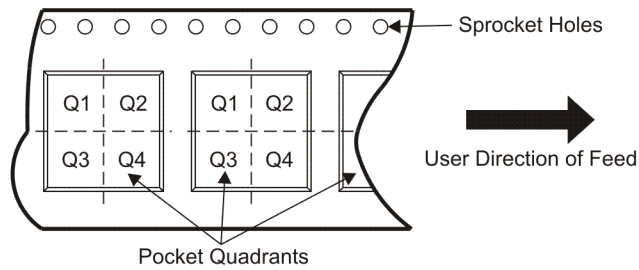
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC74MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC74MDREP	SOIC	D	14	2500	333.2	345.9	28.6

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